

Atty. Docket No. CPAC 1017-3  
Appl. No. 10/632,568

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos

Application No.: 10/632,568

Filed: August 2, 2003

Title: Semiconductor multi-package module  
having package stacked over ball grid array  
package and having wire bond interconnect)  
between stacked packages

Examiner: Douglas M. Menz

Group Art Unit: 2824

Date: December 12, 2005.

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I hereby certify that this correspondence is being facsimile transmitted to  
Examiner Menz in the United States Patent and Trademark Office, at the Central  
Fax no. 571-273-8300 on December 12, 2005.

Signed

Paula Faulk Hurley

COMMISSIONER FOR PATENTS  
P.O. Box 1450  
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Final Office action mailed August 10, 2005, kindly amend the  
application as follows.

Amendments to the claims are reflected in the **Listing of Claims**, which begins on page 2 of this  
paper.

Remarks begin on page 6 of this paper.